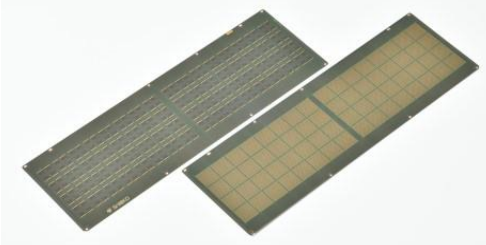
Plastic BGA Substrate

Features

■ Plastic BGA Substrate

SHINKO provides organic substrates using prepreg for BGA packages in logic, memory, and sensor devices, etc.

- 2 Layers / 4 Layers Substrate with Through Hole
  - Substrate with low cost and high reliability
  - Superior electrical characteristics

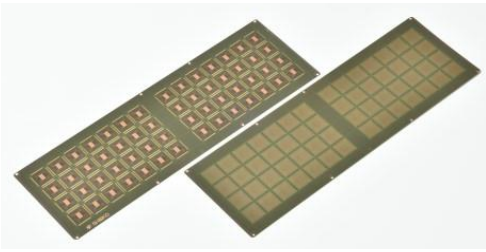


- Build-up Substrate ~IVH*~
  - Thinner substrate thickness is available by using thin core.
    (*ex.* less than 150μm total thickness with 4 layers)
  - Multilayer structure consisting of 4 or more layers is possible.
  - Available for both WB (Wire Bonding) and FC (Flip-Chip)
  - High density is possible by using semi-additive process and laser vias.
  - Structure of via on PTH (Plated Through Hole) and structure of stacked via are supported.

*IVH : Interstitial Via Hole

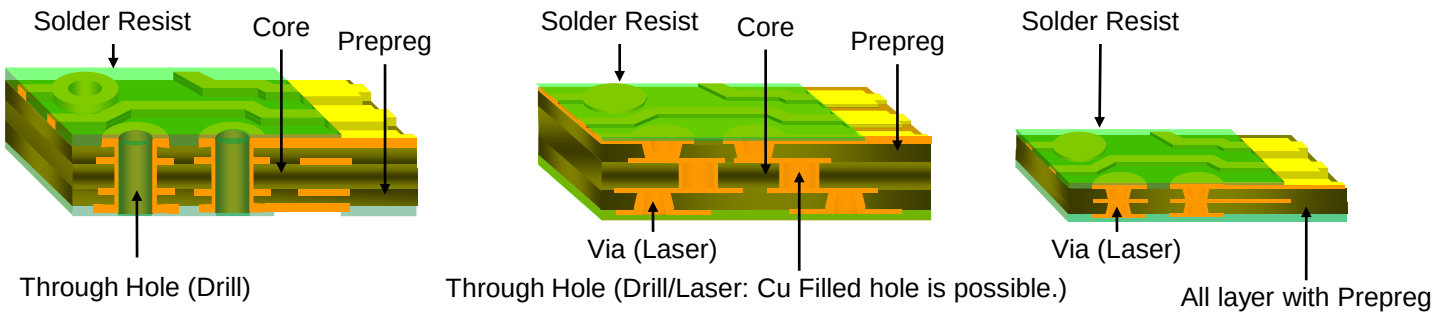
■ Plastic BGA Coreless Substrate ~IVH3~

SHINKO provides coreless substrate using IVH technology for improving performance in a thinner form factor.



- Ultimate substrate thickness reduction is possible by removing core layer.
  (*ex.* 70μm or less total thickness with 3 layers)
  (*ex.* 85μm or less total thickness with 4 layers)
- Superior electrical characteristics
- Multilayer structure consisting of 3 or more layers is possible.
- Available for both WB (Wire Bonding) and FC (Flip-Chip) interconnect
- High density is possible by using semi-additive process and laser vias.
- Structure of stacked via is supported.

Structure



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